

## 2SJ505S-VB Datasheet

### P-Channel 60-V (D-S) 175 °C MOSFET

**PRODUCT SUMMARY**

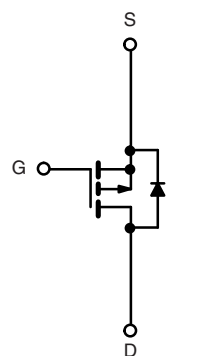
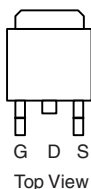
| $V_{DS}$ (V) | $R_{DS(on)}$ ( $\Omega$ )    | $I_D$ (A) <sup>d</sup> |
|--------------|------------------------------|------------------------|
| - 60         | 0.0065 at $V_{GS} = - 10$ V  | - 110                  |
|              | 0.0085 at $V_{GS} = - 4.5$ V |                        |

**FEATURES**

- TrenchFET<sup>®</sup> Power MOSFET
- Package with Low Thermal Resistance
- 100 %  $R_g$  Tested



Available

**RoHS\***  
COMPLIANT**TO-263**

P-Channel MOSFET

**ABSOLUTE MAXIMUM RATINGS**  $T_C = 25\text{ }^{\circ}\text{C}$ , unless otherwise noted

| Parameter                                                                        | Symbol         | Limit                                                     | Unit               |
|----------------------------------------------------------------------------------|----------------|-----------------------------------------------------------|--------------------|
| Drain-Source Voltage                                                             | $V_{DS}$       | - 60                                                      | V                  |
| Gate-Source Voltage                                                              | $V_{GS}$       | $\pm 20$                                                  |                    |
| Continuous Drain Current <sup>d</sup><br>( $T_J = 175\text{ }^{\circ}\text{C}$ ) | $I_D$          | $T_C = 25\text{ }^{\circ}\text{C}$<br>- 110               | A                  |
|                                                                                  |                | $T_C = 125\text{ }^{\circ}\text{C}$<br>- 75               |                    |
| Pulsed Drain Current                                                             | $I_{DM}$       | - 200                                                     |                    |
| Avalanche Current                                                                | $I_{AS}$       | - 85                                                      |                    |
| Single Pulse Avalanche Energy <sup>d</sup>                                       | $E_{AS}$       | 211                                                       | mJ                 |
| Maximum Power Dissipation                                                        | $P_D$          | $T_C = 25\text{ }^{\circ}\text{C}$<br>272 <sup>c</sup>    | W                  |
|                                                                                  |                | $T_A = 25\text{ }^{\circ}\text{C}^b$<br>3.75 <sup>b</sup> |                    |
| Operating Junction and Storage Temperature Range                                 | $T_J, T_{stg}$ | - 55 to 175                                               | $^{\circ}\text{C}$ |

**THERMAL RESISTANCE RATINGS**

| Parameter           | Symbol     | Limit | Unit                 |
|---------------------|------------|-------|----------------------|
| Junction-to-Ambient | $R_{thJA}$ | 40    | $^{\circ}\text{C/W}$ |
| Junction-to-Case    | $R_{thJC}$ | 0.55  |                      |

Notes:

a. Duty cycle  $\leq 1\%$ .

b. When Mounted on 1" square PCB (FR-4 material).

c. See SOA curve for voltage derating.

d. Limited by Package.

\* Pb containing terminations are not RoHS compliant, exemptions may apply.

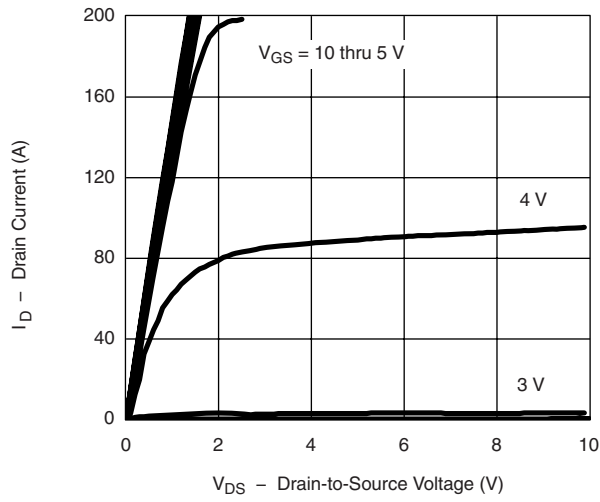
| SPECIFICATIONS T <sub>J</sub> = 25 °C, unless otherwise noted                      |                      |                                                                                                                                  |       |        |       |      |
|------------------------------------------------------------------------------------|----------------------|----------------------------------------------------------------------------------------------------------------------------------|-------|--------|-------|------|
| Parameter                                                                          | Symbol               | Test Conditions                                                                                                                  | Min.  | Typ.   | Max.  | Unit |
| Static                                                                             |                      |                                                                                                                                  |       |        |       |      |
| Drain-Source Breakdown Voltage                                                     | V <sub>(BR)DSS</sub> | V <sub>GS</sub> = 0 V, I <sub>D</sub> = - 250 μA                                                                                 | - 60  |        |       | V    |
| Gate-Threshold Voltage                                                             | V <sub>GS(th)</sub>  | V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = - 250 μA                                                                    | - 1   |        | - 3   |      |
| Gate-Body Leakage                                                                  | I <sub>GSS</sub>     | V <sub>DS</sub> = 0 V, V <sub>GS</sub> = ± 20 V                                                                                  |       |        | ± 100 | nA   |
| Zero Gate Voltage Drain Current                                                    | I <sub>DSS</sub>     | V <sub>DS</sub> = - 60 V, V <sub>GS</sub> = 0 V                                                                                  |       |        | - 1   | μA   |
|                                                                                    |                      | V <sub>DS</sub> = - 60 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C                                                         |       |        | - 50  |      |
|                                                                                    |                      | V <sub>DS</sub> = - 60 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 175 °C                                                         |       |        | - 250 |      |
| On-State Drain Current <sup>a</sup>                                                | I <sub>D(on)</sub>   | V <sub>DS</sub> = - 5 V, V <sub>GS</sub> = - 10 V                                                                                | - 120 |        |       | A    |
| Drain-Source On-State Resistance <sup>a</sup>                                      | R <sub>DS(on)</sub>  | V <sub>GS</sub> = - 10 V, I <sub>D</sub> = - 30 A                                                                                |       | 0.0065 |       | Ω    |
|                                                                                    |                      | V <sub>GS</sub> = - 10 V, I <sub>D</sub> = - 30 A, T <sub>J</sub> = 125 °C                                                       |       | 0.0129 |       |      |
|                                                                                    |                      | V <sub>GS</sub> = - 10 V, I <sub>D</sub> = - 30 A, T <sub>J</sub> = 175 °C                                                       |       | 0.016  |       |      |
|                                                                                    |                      | V <sub>GS</sub> = - 4.5 V, I <sub>D</sub> = - 20 A                                                                               |       | 0.0085 |       |      |
| Forward Transconductance <sup>a</sup>                                              | g <sub>fs</sub>      | V <sub>DS</sub> = - 15 V, I <sub>D</sub> = - 50 A                                                                                | 20    |        |       | S    |
| Dynamic <sup>b</sup>                                                               |                      |                                                                                                                                  |       |        |       |      |
| Input Capacitance                                                                  | C <sub>iss</sub>     | V <sub>GS</sub> = 0 V, V <sub>DS</sub> = - 25 V, f = 1 MHz                                                                       |       | 9200   |       | pF   |
| Output Capacitance                                                                 | C <sub>oss</sub>     |                                                                                                                                  |       | 975    |       |      |
| Reverse Transfer Capacitance                                                       | C <sub>rss</sub>     |                                                                                                                                  |       | 760    |       |      |
| Total Gate Charge <sup>c</sup>                                                     | Q <sub>g</sub>       | V <sub>DS</sub> = - 30 V, V <sub>GS</sub> = - 10 V, I <sub>D</sub> = - 110 A                                                     |       | 160    | 240   | nC   |
| Gate-Source Charge <sup>c</sup>                                                    | Q <sub>gs</sub>      |                                                                                                                                  |       | 40     |       |      |
| Gate-Drain Charge <sup>c</sup>                                                     | Q <sub>gd</sub>      |                                                                                                                                  |       | 36     |       |      |
| Gate Resistance                                                                    | R <sub>g</sub>       | f = 1 MHz                                                                                                                        | 1.5   | 3      | 4.5   | Ω    |
| Turn-On Delay Time <sup>c</sup>                                                    | t <sub>d(on)</sub>   | V <sub>DD</sub> = - 30 V, R <sub>L</sub> = 0.27 Ω<br>I <sub>D</sub> ≅ - 110 A, V <sub>GEN</sub> = - 10 V, R <sub>G</sub> = 2.5 Ω |       | 20     | 30    | ns   |
| Rise Time <sup>c</sup>                                                             | t <sub>r</sub>       |                                                                                                                                  |       | 190    | 285   |      |
| Turn-Off Delay Time <sup>c</sup>                                                   | t <sub>d(off)</sub>  |                                                                                                                                  |       | 140    | 210   |      |
| Fall Time <sup>c</sup>                                                             | t <sub>f</sub>       |                                                                                                                                  |       | 300    | 450   |      |
| Source-Drain Diode Ratings and Characteristics T <sub>C</sub> = 25 °C <sup>b</sup> |                      |                                                                                                                                  |       |        |       |      |
| Continuous Current                                                                 | I <sub>S</sub>       |                                                                                                                                  |       |        | - 110 | A    |
| Pulsed Current                                                                     | I <sub>SM</sub>      |                                                                                                                                  |       |        | - 200 |      |
| Forward Voltage <sup>a</sup>                                                       | V <sub>SD</sub>      | I <sub>F</sub> = - 50 A, V <sub>GS</sub> = 0 V                                                                                   |       | - 1.0  | - 1.5 | V    |
| Reverse Recovery Time                                                              | t <sub>rr</sub>      | I <sub>F</sub> = - 50 A, di/dt = 100 A/μs                                                                                        |       | 60     | 90    | ns   |
| Peak Reverse Recovery Charge                                                       | I <sub>RM(REC)</sub> |                                                                                                                                  |       | - 3    | - 4.5 | A    |
| Reverse Recovery Charge                                                            | Q <sub>rr</sub>      |                                                                                                                                  |       |        | 0.09  | 0.2  |

Notes:

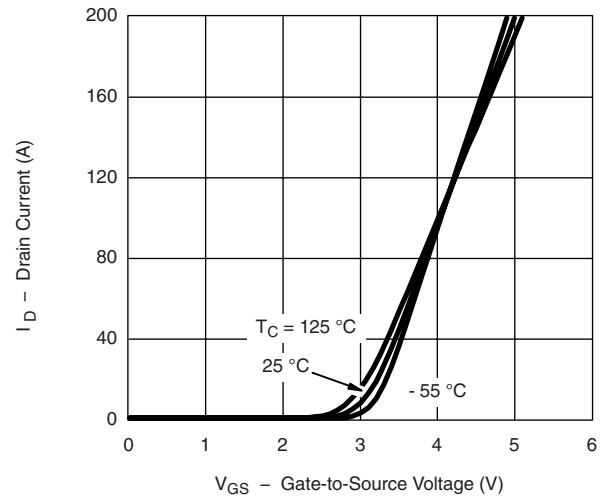
- a. Pulse test; pulse width  $\leq 300\text{ }\mu\text{s}$ , duty cycle  $\leq 2\%$ .  
 b. Guaranteed by design, not subject to production testing.  
 c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

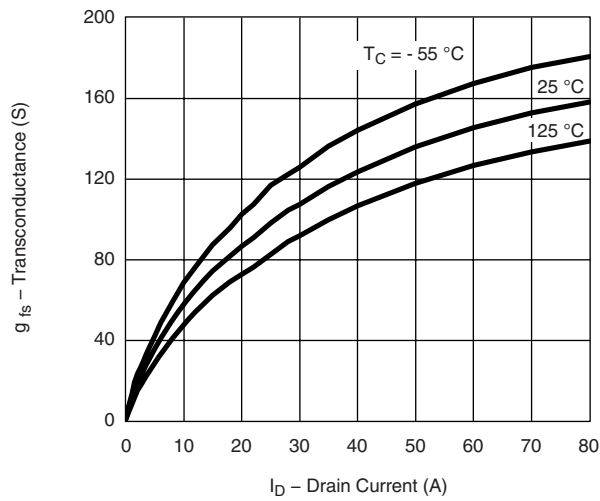
**TYPICAL CHARACTERISTICS** 25 °C, unless otherwise noted



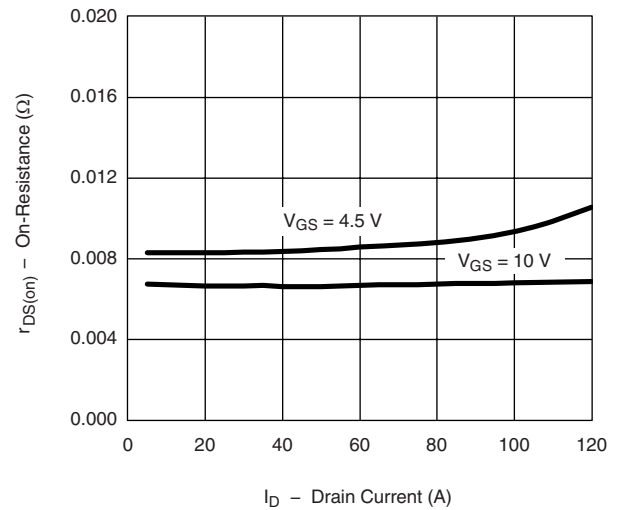
**Output Characteristics**



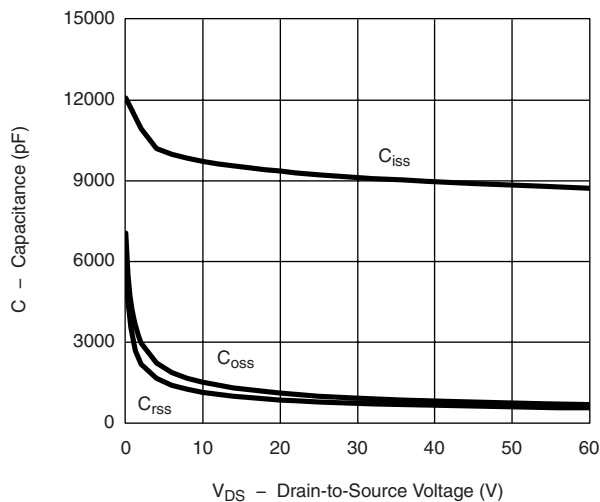
**Transfer Characteristics**



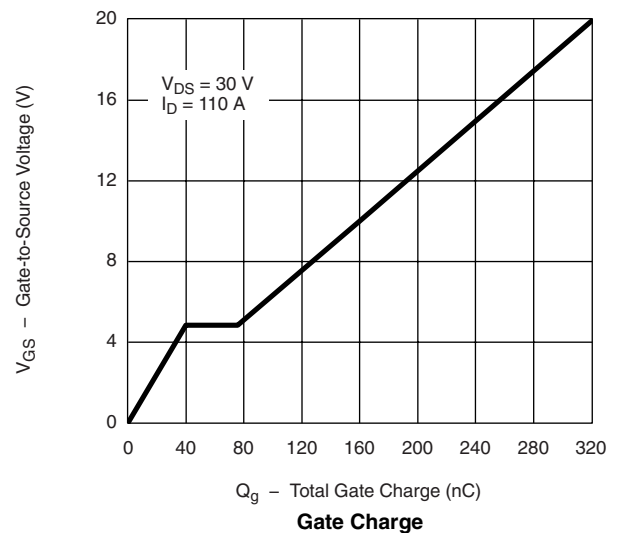
**Transconductance**



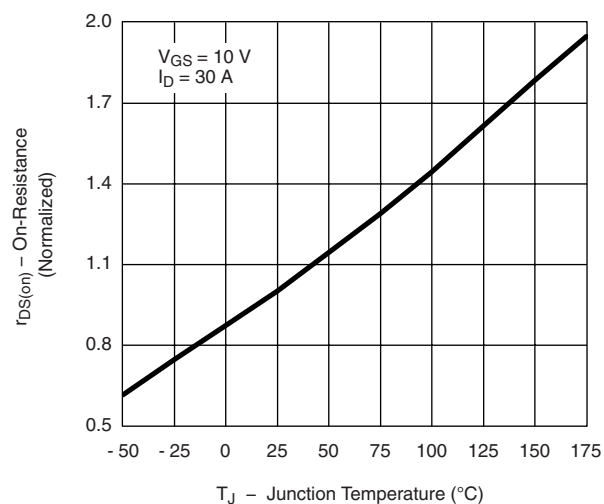
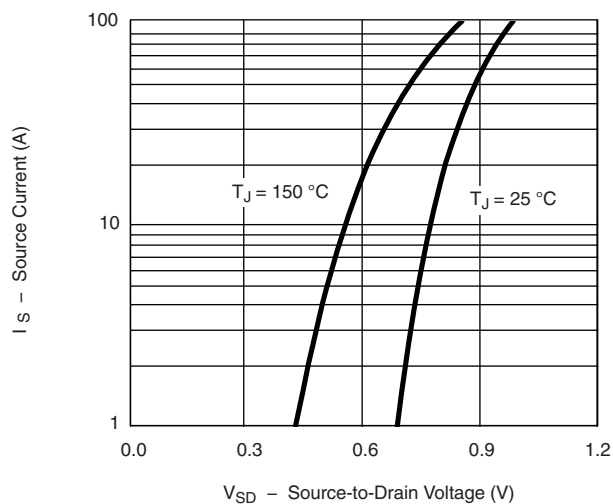
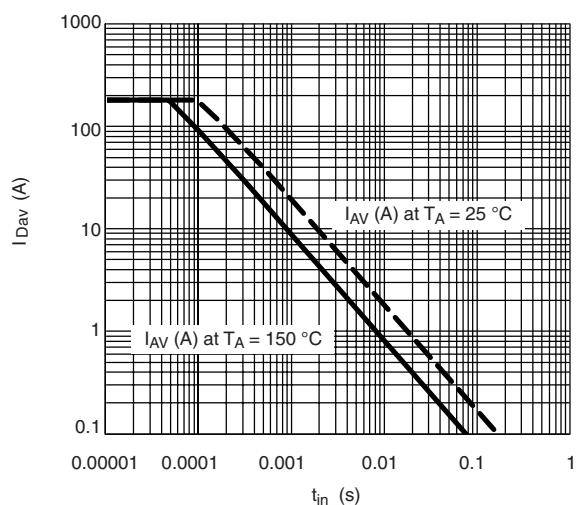
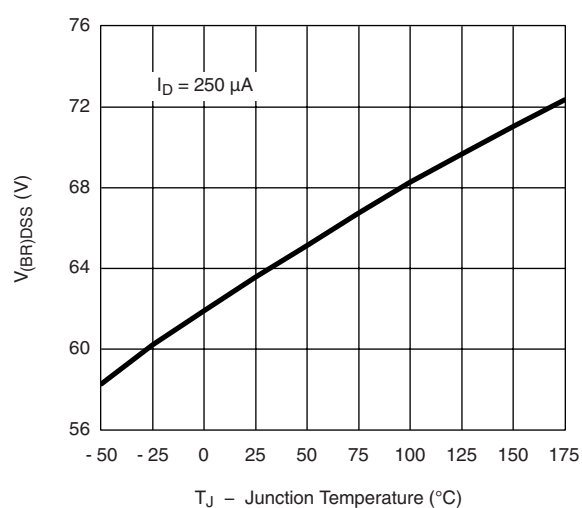
**On-Resistance vs. Drain Current**



**Capacitance**



**Gate Charge**

**TYPICAL CHARACTERISTICS** 25 °C, unless otherwise noted

**On-Resistance vs. Junction Temperature**

**Source-Drain Diode Forward Voltage**

**Avalanche Current vs. Time**

**Drain Source Breakdown vs. Junction Temperature**

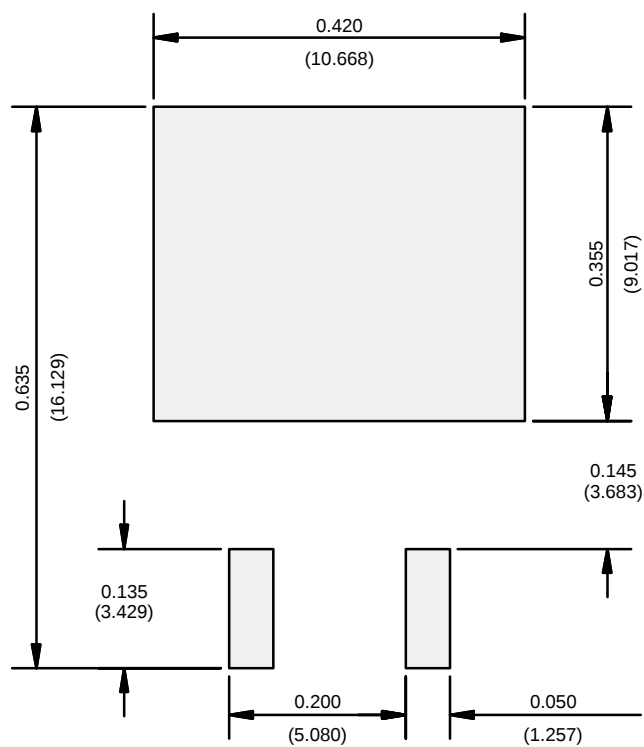
The graph shows the relationship between Drain Current ( $I_D$ ) in Amperes (A) and Case Temperature ( $T_C$ ) in degrees Celsius ( $^{\circ}\text{C}$ ) for the 2N3866 JFET. The solid line indicates the continuous drain current, which is limited by the package and remains constant at approximately 110 A up to 75  $^{\circ}\text{C}$ . Beyond 75  $^{\circ}\text{C}$ , the current decreases as temperature increases. The dashed line represents the pulsed drain current, which starts at approximately 140 A at 0  $^{\circ}\text{C}$  and decreases linearly to about 110 A at 75  $^{\circ}\text{C}$ .

| $T_C$ ( $^{\circ}\text{C}$ ) | Continuous $I_D$ (A) | Pulsed $I_D$ (A) |
|------------------------------|----------------------|------------------|
| 0                            | 110                  | 140              |
| 25                           | 110                  | 132              |
| 50                           | 110                  | 124              |
| 75                           | 110                  | 110              |
| 100                          | 95                   | -                |
| 125                          | 75                   | -                |
| 150                          | 50                   | -                |
| 175                          | 0                    | -                |

Figure 10 is a Safe Operating Area (SOA) graph for the 2N7000 MOSFET. The y-axis represents Drain Current ( $I_D$ ) in Amperes (A) on a logarithmic scale from 0.1 to 1000. The x-axis represents Drain-to-Source Voltage ( $V_{DS}$ ) in Volts (V) on a logarithmic scale from 0.1 to 100. The graph shows the maximum allowable drain current for various pulse widths: 10  $\mu$ s (solid line), 100  $\mu$ s (dashed line), 1 ms (dash-dot line), 10 ms (dotted line), and 100 ms, DC (thick solid line). The SOA is limited by  $r_{DS(on)}$  for  $V_{DS} < 10$  V and by thermal limits for  $V_{DS} > 10$  V. The graph is for  $T_C = 25^\circ\text{C}$  and Single Pulse.



**RECOMMENDED MINIMUM PADS FOR D<sup>2</sup>PAK: 3-Lead**



Recommended Minimum Pads  
Dimensions in Inches/(mm)

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